

MA2S377

Silicon epitaxial planar type

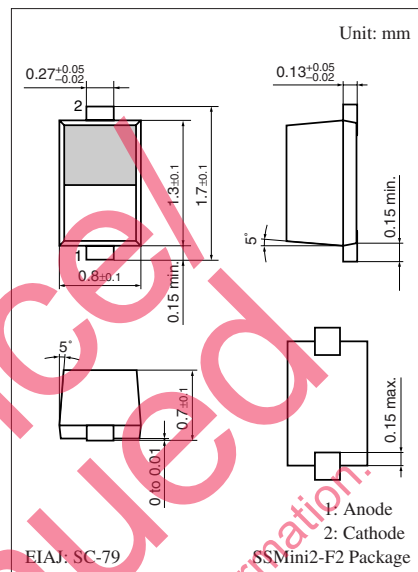
For VCO, VCXO and TCXO

■ Features

- SS-Mini type package, allowing downsizing of equipment and automatic insertion through the taping package

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	12	V
Forward current	I_F	20	mA
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$



Marking Symbol: 7

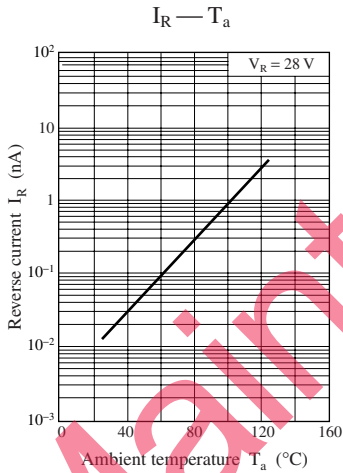
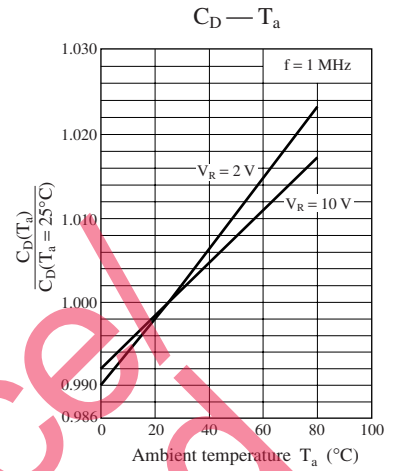
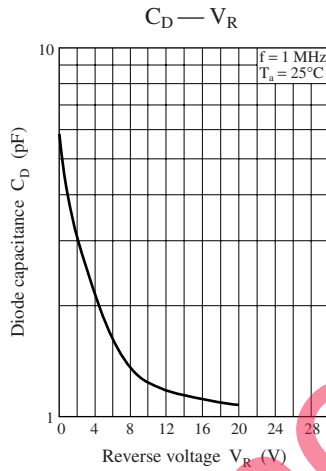
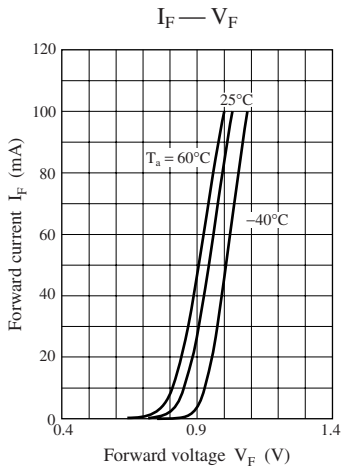
■ Electrical Characteristics $T_a = 25 \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse current	I_R	$V_R = 12\text{ V}$			10	nA
Diode capacitance	$C_{D(2V)}$	$V_R = 2\text{ V}, f = 1\text{ MHz}$	2.80		3.40	pF
	$C_{D(10V)}$	$V_R = 10\text{ V}, f = 1\text{ MHz}$	1.10		1.50	
Capacitance ratio	$C_{D(2V)} / C_{D(10V)}$		2.20		2.80	—
Series resistance *	r_D	$C_D = 9\text{ pF}, f = 470\text{ MHz}$		0.40	0.60	Ω

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 470 MHz.

3. *: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER



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